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3. 1. A semiconductor device, comprising:
a plurality of semiconductor elements arranged on
5 a substrate; and
a main current electrode which is arranged
vertically to a surface of the substrate and apart from
a neighborhood of said plurality of semiconductor
elements, wherein
10 each of said plurality of semiconductor elements
and said main current electrode are electrically
connected.
2. The semiconductor device according to claim 1,
15 wherein
each of said plurality of semiconductor elements
and said main current electrode are connected by wire
bonding.
- 20 3. The semiconductor device according to claim 1,
wherein
said plurality of semiconductor elements are
switching elements.
- 25 4. The semiconductor device according to claim 1,

further comprising

a thermal conductor member at a bottom of the semiconductor device, wherein

5 said plurality of semiconductor elements are directly or indirectly connected to said thermal conductor member so that they are thermally coupled.

5. The semiconductor device according to claim 4, wherein

10 said thermal conductor member is formed with a ceramic material.

6. The semiconductor device according to claim 1, wherein

15 said plurality of semiconductor elements are arranged in one row or a plurality of rows.

7. A semiconductor device including one or a plurality of semiconductor elements, comprising:

20 a substrate on which the one or the plurality of semiconductor elements are arranged;

a case that is arranged in a predetermined position relative to said substrate so that the one or the plurality of semiconductor elements are surrounded; and

25 a metal member on which a main current electrode

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of the one or the plurality of semiconductor elements and a terminal for electrically connecting said semiconductor device and a circuit external to said semiconductor device are formed integrally, wherein

5 said metal member is arranged in a position apart from said substrate by using said case.

8. The semiconductor device according to claim 7, wherein

note 

10 said metal member is arranged above the one or the plurality of semiconductor elements or a wiring pattern connected to the one or the plurality of semiconductor elements.

15 9. The semiconductor device according to claim 7, wherein

 said metal member and the semiconductor device are electrically connected by wire bonding.

20 10. The semiconductor device according to claim 7, wherein:

 said case includes a frame portion surrounding the one or the plurality of semiconductor elements; and

 said metal member is fixed to the frame portion
25 of said case.